

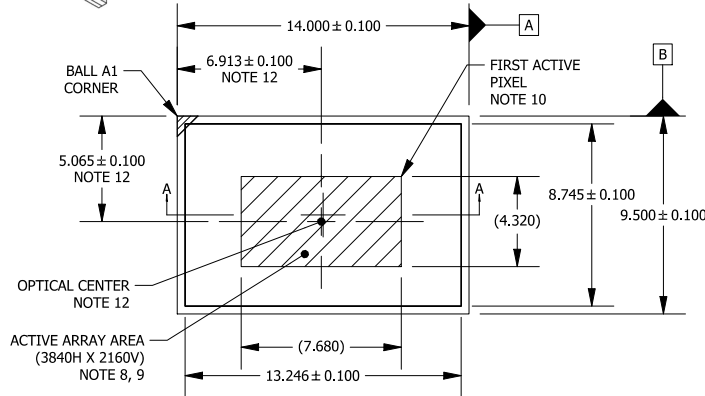
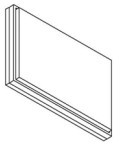
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

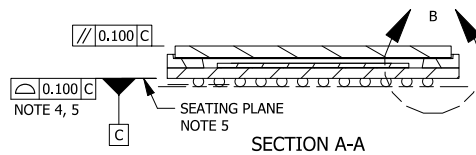


PBGA75 14x9.5 CASE 117CU ISSUE O

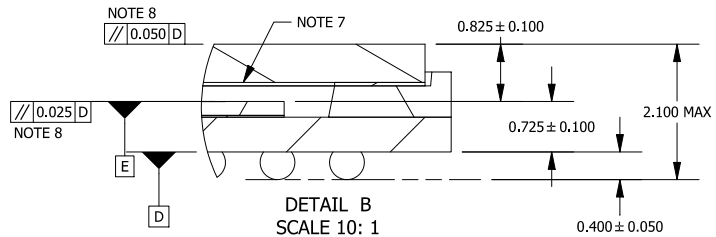
DATE 12 MAY 2020



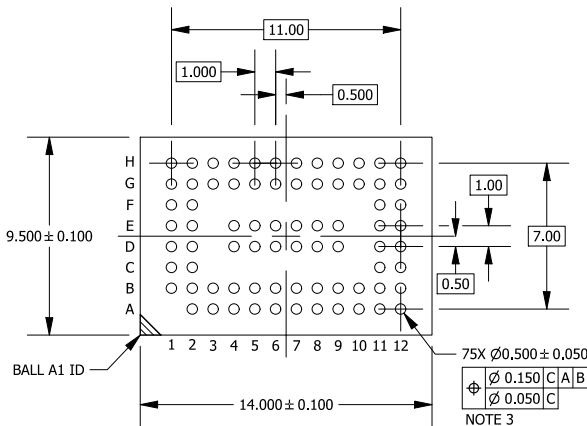
TOP VIEW



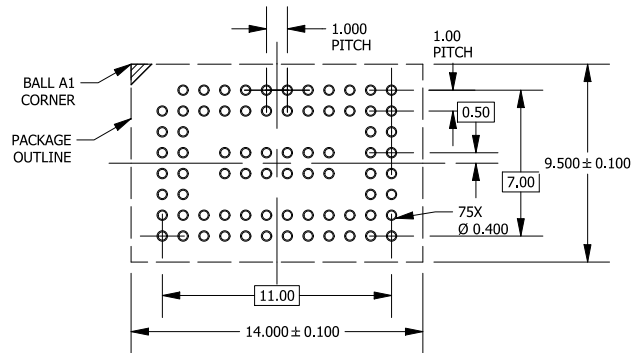
SECTION A-A



DETAIL B
SCALE 10: 1



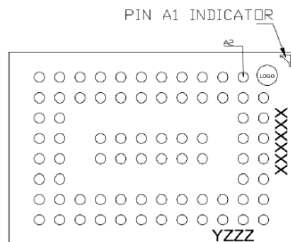
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.550 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.275 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ± 1°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.087, -0.315).

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DESCRIPTION:	PBGA75 14x9.5	PAGE 1 OF 1

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